



Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.		This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.	
		Adobe Reader version 7.0.5 is required to complete this declaration.	
IPC-1752-1 v1.02	IPC Web Site for Information on IPC-1752 Standard http://www.ipc.org/IPC-175x	Form Type *	Declaration Class *

Supplier Information									
Company Name *		Company Unique ID	Unique ID Authority	Response Date *		Response Document ID			
Contact Name *		Title - Contact	Phone - Contact *	Email - Contact *					
Authorized Representative *		Title - Representative	Phone - Representative *	Email - Representative *		Supplier Comments or URL for Additional Information			
	Requester Item Number	Mfr Item Number	Mfr Item Name	Effective Date	Version	Manufacturing Site	Weight	UOM	Unit Type
	Alternate Recommendation				Alternate Item Comments				

Manufacturing Information section intentionally omitted.

Save the fields in this form to a file	Import fields from a file into this form	Clear all of the fields on this form	Lock the fields on this form to prevent changes
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RoHS Material Composition Declaration		Declaration Type *	
	RoHS Definition: Quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material for Cadmium		
RoHS Declaration *			Supplier Acceptance
Exemptions: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and checkboxes will appear below. Check all applicable exemptions.			
<div> <div> 1. Mercury in compact fluorescent lamps not exceeding 5 mg per lamp. 2a. Mercury in straight fluorescent lamps for general purposes not exceeding 10 mg. in halophosphate lamps 2b. Mercury in straight fluorescent lamps for general purposes not exceeding 5 mg. in triphosphate lamps with a normal lifetime 2c. Mercury in straight fluorescent lamps for general purposes not exceeding 8 mg. in triphosphate lamps with long lifetime 3. Mercury in straight fluorescent lamps for special purposes. 4. Mercury in other lamps not specifically mentioned in this list. 5. Lead in glass of cathode ray tubes, electronic components and fluorescent tubes. 6a. Lead as an alloying element in steel containing up to 0.35% lead by weight. 6b. Lead as an alloying element in aluminum containing up to 0.4% lead by weight. 6c. Lead as an alloying element in copper containing up to 4% lead by weight. 7a. Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead). 7b. Lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signalling, transmission as well as network management for telecommunications. </div> <div> 7c. Lead in electronic ceramic parts (e.g. piezoelectronic devices). 8. Cadmium and its compounds in electrical contacts and cadmium plating except for applications banned under Directive 91/338/EEC amending Directive 76/769/EEC relating to restrictions on the marketing and use of certain dangerous substances and preparations piezoelectronic devices). 9. Hexavalent chromium as an anti-corrosion of the carbon steel cooling system in absorption refrigerators 10a. Deca BDE in polymeric applications 10b. Lead in lead/bronze bearing shells and bushes 11. Lead used in compliant pin connector systems. 12. Lead as a coating material for a thermal conduction module c-ring. 13a. Lead in optical and filter glass. 13b. Cadmium in optical and filter glass. 14. Lead in solders consisting of more than two elements for the connection between the pins and the package of microprocessors with a lead content of more than 80% and less than 85% by weight . 15. Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit Flip Chip packages. </div> </div>			

Declaration Signature	
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.	
Supplier Digital Signature	

Joint Industry Guide (JIG) Material Composition Declaration for Electronic Products

Instructions: Declare whether the item substances exceed the threshold levels shown in the table and report accordingly. Where threshold levels include the words "intentionally added", substances must be declared if they are added intentionally, regardless of threshold level. For each RoHS substance, identified with dual asterisks (**), report the worst case PPM at the homogeneous material level and optionally the total weight of the substance in the item. For all remaining (non-RoHS) JIG A & B substances, and any additional substances, report the total weight and optionally the PPM at the part level for each item.

[illegible]

OTHER Material Composition Declaration

Requester Instructions: The requester can optionally include additional substances that must be declared for the item on this form. This is in addition to JIG Level A and JIG Level B substances. The requester should enter additional substances as well as the threshold levels that specify the substance at the item level.

Supplier Instructions: Explicitly declare whether the item exceed the threshold level by selecting Yes or No. If the maximum concentration of any substance exceeds the threshold levels defined by the requester, then the substance content must be reported in total weight and/or worst case PPM, along with a description of material use.

JIG	Category Name	Threshold Level
Other	As defined by the Requester	Defined by the Requester